



Part Number :	MA006	Date:	22 November 2005
Customer:	M/A Com	STD:	Y
Customer Specification/ Reference:			

Category	Parameter	Specification	Measurement Method
<i>Overall</i>			
<i>Wafer</i>			
1.1	Diameter	100 +/- 0.5 mm	Wafer Vendor
1.2	Primary Flat Orientation	{1-10} +/- 1°	Wafer Vendor
1.3	Primary Flat Length	32.5 +/- 2.5 mm	Wafer Vendor
1.4	Secondary Flat Orientation	None	
1.5	Thickness	525 µm +/- 5 µm**	ADE, 100%
1.6	Total Thickness Variation(TTV)	< 5µm	Guaranteed by Process
1.7	Bow	< 50 µm	ADE to ASTM F534, 20%
1.9	Warp	< 50 µm	ADE to ASTM F657, 20%
1.9	Edge Chips	0	Bright Light, 100% ¹
1.10	Defect Exclusion Radius	5mm	
<i>Handle</i>			
<i>Silicon</i>			
2.1	Growth Method	CZ	Wafer Vendor
2.2	Orientation	{100} +/- 1 degree	Wafer Vendor
2.3	Thickness	513 µm +/- 5µm**	ADE, 100%
2.4	Doping type	N	Wafer Vendor
2.5	Dopant	Phosphorous	Wafer Vendor
2.6	Resistivity	<0.003 Ω-cm	Wafer Vendor
2.7	Backside Finish	Lapped and etched with no oxide and lasermark	Wafer Vendor

Category	Parameter	Specification	Measurement Method
<i>Device</i>			
<i>Silicon</i>			
4.1	Growth Method	FZ	Wafer Vendor
4.2	Orientation	{100} +/- 0.5 degree	Wafer Vendor
4.3	Nominal Thickness	12 um	FTIR, 100%
4.4	Thickness Variation	+/- 0.5um	FTIR, 100% 9-Pt ²
4.5	Distance to device silicon edge from wafer edge	<2mm	Guaranteed by process
4.6	Doping Type	N	Wafer Vendor
4.7	Dopant	Phosphorous	Wafer Vendor
4.8	Resistivity	> 4000 Ω-cm	Wafer Vendor
4.9	Device Side Scribe	None	
4.10	Voids	0	Bright Light, 100% ¹
4.11	Scratches	0	Bright Light, 100% ¹
4.12	Haze	None	Bright Light, 100% ¹

** For initial sampling of this product, M/A Com have supplied the handle material. IceMOS will make the Handle of the SI-Si wafer as close to 513um as the original thickness of the starting material permits. This will be confirmed upon receipt of the material

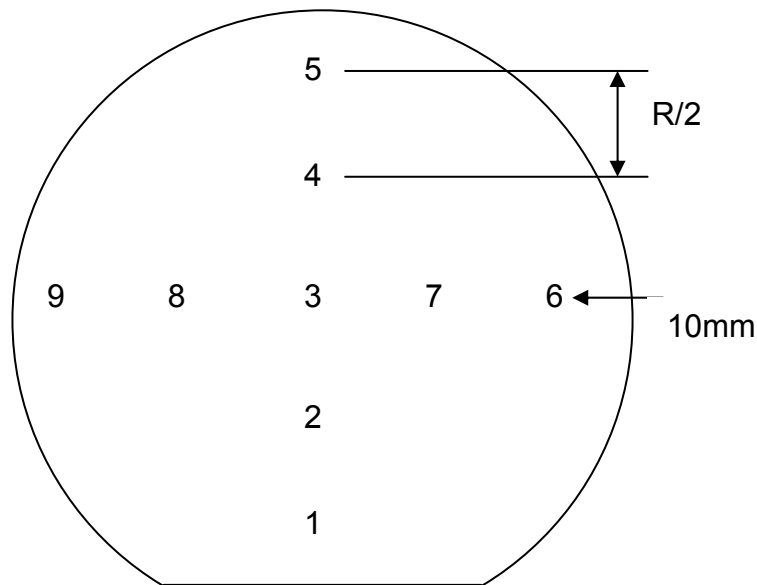
*Shipping
Details*

Wafers per box	MAX 25
Packaging	Taped Polypropylene Wafer Box Empak, Ultrapak, 100mm Antistatic Double Bagging
Lot Shipment Data :	Device Silicon Thickness Bow/Warp Data

Explanatory Notes

1. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in 1.10. High intensity bright lamp inspection as per ASTM F523.

2. 9 point measurement are as shown in the diagram below:



Approvals:	Quality:	Engineering:
	Marketing:	TRB:

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